JP \$40.00 11617

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Greg M. Hoff	01/10/2007
Dan Leeuw	01/10/2007
Ed Poorman	01/15/2007

RECEIVING PARTY DATA

Name:	ITT Manufacturing Enterprises, Inc.	
Street Address:	1105 North Market Street	
Internal Address:	Suite 1217	
City:	Wilmington	
State/Country:	DELAWARE	
Postal Code:	19801	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11617786

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	0918.0344C
NAME OF SUBMITTER:	Andrew J. Aldag

PATENT REEL: 018776 FRAME: 0326

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Total Attachments: 1

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PATENT REEL: 018776 FRAME: 0327

ASSIGNMENT

For good and valuable consideration, I/WE, Greg M. Hoff, a citizen of the U.S.A., residing at 431 Ridge Hill Place, Fort Wayne IN 46804; Dan Leeuw, a citizen of the U.S.A., residing at 6226 Heritage Oaks Place, Fort Wayne, IN 46835; and Ed Poorman, a citizen of the U.S.A., residing at 11508 Hand Rd. Fort Wayne IN 46818hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to ITT Manufacturing Enterprises, Inc., a corporation duly organized and existing under the laws of the state of Delaware and having a place of business at 1105 North Market Street, Suite 1217, Wilmington, Delaware, 19801 hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in U.S. Patent Application Serial No. 11/617,786, which has been executed by the undersigned, entitled:

Connectors to Connect Modules to Electronic Devices

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, it successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: Teg M. Hoff

SIGNATURE: Dan Leeuw D

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RECORDED: 01/19/2007